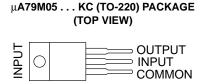
SLVS060J - JUNE 1976 - REVISED MAY 2003

- 3-Terminal Regulators
- Output Current Up To 500 mA
- No External Components

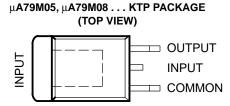


 $\mu$ A79M05 . . . KCS (TO-220) PACKAGE (TOP VIEW)



#### High Power-Dissipation Capability

- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation



#### description/ordering information

This series of fixed-negative-voltage integrated-circuit voltage regulators is designed to complement the  $\mu$ A78M00 series in a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators delivers up to 500 mA of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also as the power-pass element in precision regulators.

#### ORDERING INFORMATION

TJ	V <sub>O</sub> (NOM) (V)	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 125°C	-5	Power Flex (KTP)	Reel of 3000	μΑ79M05CKTPR	μΑ79M05C
		TO-220 (KC)	Tube of 50	μΑ79M05CKC	μΑ79M05C
		TO-220, short shoulder (KCS)	Tube of 20	μΑ79M05CKCS	μΑ/9Μ05C
	-8	Power Flex (KTP)	Reel of 3000	μΑ79M08CKTPR	μΑ79M08C

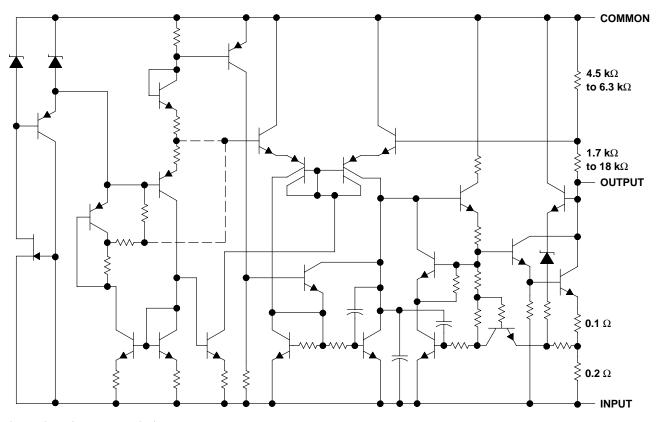
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### schematic



Resistor values shown are nominal.

#### absolute maximum ratings over virtual junction temperature range (unless otherwise noted)

Input voltage, V <sub>I</sub>	35 V
Operating virtual junction temperature, T <sub>J</sub>	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stg</sub> –65°C to	150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### package thermal data (see Note 1)

PACKAGE	BOARD	θJC	$AL^{\theta}$
POWER-FLEX (KTP)	High K, JESD 51-5	19°C/W	28°C/W
TO-220 (KC/KCS)	High K, JESD 51-5	3°C/W	19°C/W

NOTE 1: Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.



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#### recommended operating conditions

			MIN	MAX	UNIT
VI	Input voltage	μΑ79M05C	-7	-25	٧
	input voitage	μΑ79M08C	-10.5	-25	l v
lo	Output current			500	mA
TJ	Operating virtual junction temperature		0	125	°C

# electrical characteristics at specified virtual junction temperature, $V_I$ = -10 V, $I_O$ = 350 mA, $T_J$ = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			μ <b>Α79M05C</b>			LINUT	
PARAMETER				MIN	TYP	MAX	UNIT	
Output voltage	$V_{ } = -7 \text{ V to } -25 \text{ V},$	I <sub>O</sub> = 5 mA to 350 mA		-4.8	<b>-</b> 5	-5.2	V	
			$T_J = 0^{\circ}C$ to $125^{\circ}C$	-4.75		-5.25	]	
Input voltage regulation	$V_{I} = -7 \text{ V to } -25 \text{ V}$				7	50	mV	
input voitage regulation	$V_{I} = -8 \text{ V to } -18 \text{ V}$				3	30	mv	
Diamin minution	V <sub>I</sub> = -8 V to -18 V, f = 120 Hz	$I_O = 100 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$	50			dB	
Ripple rejection		I <sub>O</sub> = 300 mA		54	60		иь	
Output voltage regulation	$I_O = 5 \text{ mA to } 500 \text{ mA}$				75	100	mV	
Output voltage regulation	$I_O = 5 \text{ mA to } 350 \text{ mA}$				50		1110	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	$T_J = 0$ °C to 125°C			-0.4		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz				125		μV	
Dropout voltage					1.1		V	
Bias current					1	2	mA	
Bias current change	$V_I = -8 \text{ V to } -18 \text{ V},$	T <sub>J</sub> = 0°C to 125°C				0.4	A	
	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	T <sub>J</sub> = 0°C to 125°C				0.4	mA	
Short-circuit output current	V <sub>I</sub> = -30 V				140		mA	
Peak output current					0.65		Α	

T Pulse-testing techniques maintain T<sub>J</sub> as close to T<sub>A</sub> as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 2-μF capacitor across the input and a 1-μF capacitor across the output.



# $\mu\text{A79M00}$ SERIES NEGATIVE-VOLTAGE REGULATORS

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## electrical characteristics at specified virtual junction temperature, $V_I = -19 \text{ V}$ , $I_O = 350 \text{ mA}$ , $T_J = 25 ^{\circ}\text{C}$ (unless otherwise noted)

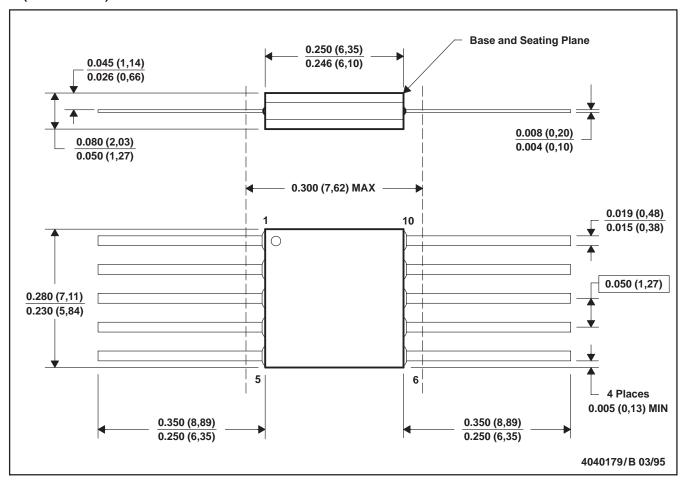
DADAMETED	TEST CONDITIONS†			μ <b>Α79M08C</b>			LINIT	
PARAMETER				MIN	TYP	MAX	UNIT	
Output voltage	V <sub>I</sub> = -10.5 V to -25 V,	I <sub>O</sub> = 5 mA to 350 mA		-7.7	-8	-8.3	V	
			$T_J = 0$ °C to 125°C	-7.6		-8.4	V	
longit voltage regulation	$V_I = -10.5 \text{ V to } -25 \text{ V}$				8	80	.,	
Input voltage regulation	V <sub>I</sub> = -11 V to -21 V			4 50			mV	
Disale seientien	$V_I = -11.5 \text{ V to } -21.5 \text{ V},$	I <sub>O</sub> = 100 mA,	$T_J = 0$ °C to 125°C	50			JD.	
Ripple rejection	f = 120 Hz	IO = 300 mA		54	59		dB	
Output voltage regulation	I <sub>O</sub> = 5 mA to 500 mA				90	160	) mV	
	I <sub>O</sub> = 5 mA to 350 mA				60		IIIV	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA,	T <sub>J</sub> = 0°C to 125°C			-0.6		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz				200		μV	
Dropout voltage	I <sub>O</sub> = 5 mA				1.1		V	
Bias current					1	2	mA	
Bias current change	$V_I = -10.5 \text{ V to } -25 \text{ V},$	T <sub>J</sub> = 0°C to 125°C				0.4	mA	
	$I_O = 5 \text{ mA to } 350 \text{ mA},$	T <sub>J</sub> = 0°C to 125°C				0.4		
Short-circuit output current	V <sub>I</sub> = -30 V				140		mA	
Peak output current					0.65		Α	

<sup>†</sup> Pulse-testing techniques maintain T<sub>J</sub> as close to T<sub>A</sub> as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 2-μF capacitor across the input and a 1-μF capacitor across the output.



#### U (S-GDFP-F10)

#### **CERAMIC DUAL FLATPACK**

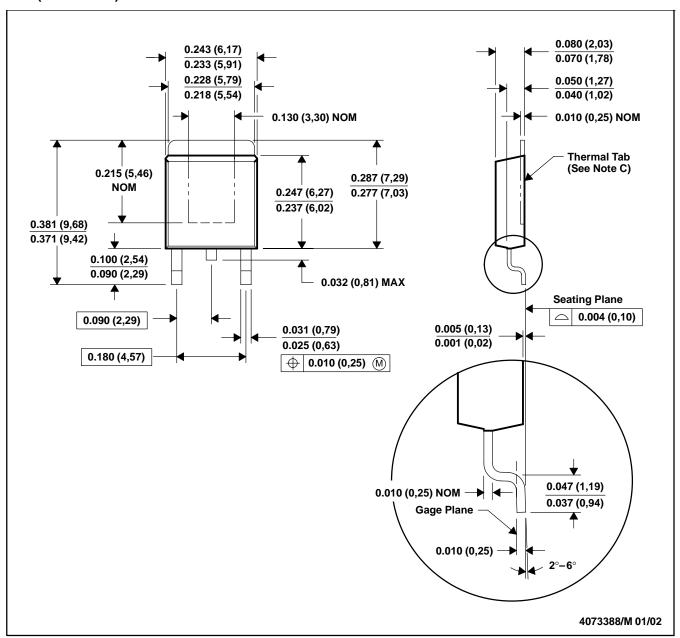


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

#### KTP (R-PSFM-G2)

#### PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

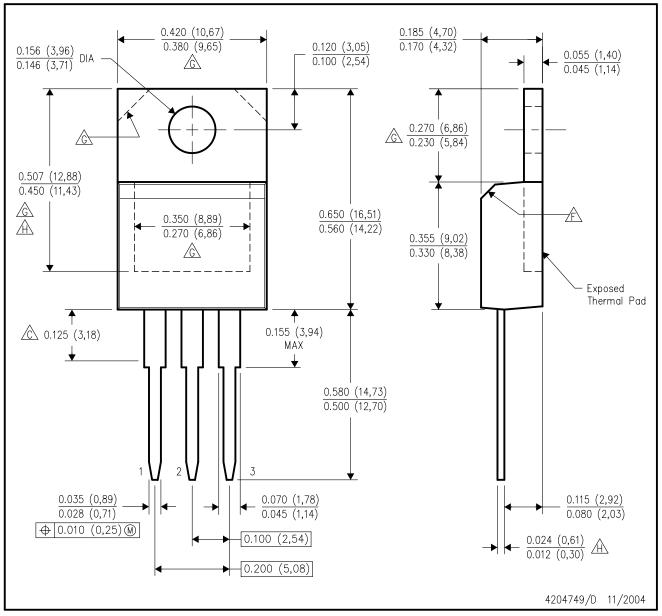
- B. This drawing is subject to change without notice.
- C. The center lead is in electrical contact with the thermal tab.
- D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
- E. Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.



## KCS (R-PSFM-T3)

#### PLASTIC FLANGE-MOUNT PACKAGE



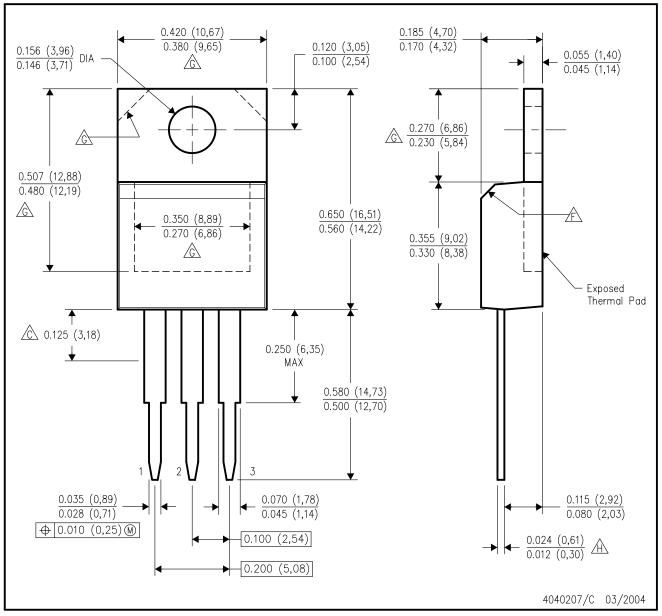
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- ⚠ Falls within JEDEC T0—220 variation AB, except minimum lead thickness and minimum exposed pad length.



## KC (R-PSFM-T3)

#### PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



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